

Flip Chip
 With SnPb or SnAgCu Bumps
 UBM and Passivation Geometries

Bumps	Die Size	Pitch	Metal Thickness	Passivation Thickness	Bump Height	Passivation Type	UBM Metal Composition	Die Thickness	Bump Types
FC48 FC98	6.3mm 12.7mm	457um (18mil)	17K Angstroms	10K Angstroms	140 Micron	Nitride	Al 98 Cu 1.0 Si 1.0	600 ~ 650 micron (24mil Av)	Standard: Sn63/Pb37 - Lead Free: Sn95.5 Ag3.5 Cu1.0
FC88 FC176 FC220	5mm 10mm 10x15mm	204um (8mil)	17K Angstroms	8K Angstroms	112 Micron				
FC317 FC1268 FC2853 FC5072	5mm 10mm 15mm 20mm	254um (10mil)	17K Angstroms	10K Angstroms	125 Micron				
FC112	5mm	152um (6mil)	8.9K Angstroms	8.0K Angstroms	85 Micron				

Bumpless Flip Chip
 For Wire Bonding
 UBM and Passivation Geometries

Bumps	Die Size	Pitch	Metal Thickness	Passivation Thickness	Standard Passivation Opening	Passivation Type	UBM Metal Composition	Die Thickness
FC48 FC98	6.3mm 12.7mm	457um (18mil)	17K Angstroms	10K Angstroms	102 ~150 Micron	Nitride	Al 98 Cu 1.0 Si 1.0	600 ~ 650 micron (24mil Av)
FC88 FC176 FC220	5mm 10mm 10x15mm	204um (8mil)	17K Angstroms	8K Angstroms	80~100 Micron			
FC317 FC1268 FC2853 FC5072	5mm 10mm 15mm 20mm	254um (10mil)	17K Angstroms	10K Angstroms	80~100 Micron			
FC112	5mm	152um (6mil)	8.9K Angstroms	8.0K Angstroms	55~86 Micron			